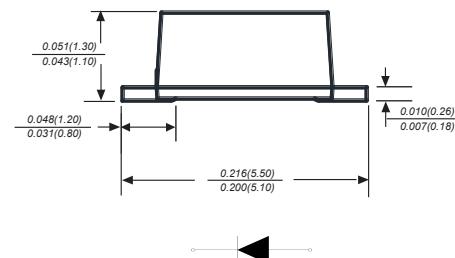
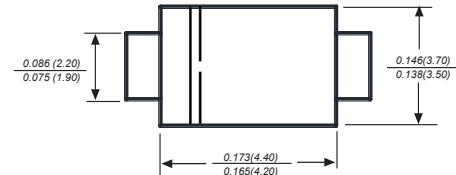




SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
- ◆ 250°C/10 seconds at terminals
- Glass passivated chip junction

SMBF

Dimensions in inches and (millimeters)

Mechanical Data**Case :** JEDEC SMBF Molded plastic body**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026**Polarity :** Polarity symbol marking on body**Mounting Position :** Any**Weight :** 0.002 ounce, 0.075 grams**Maximum Ratings And Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES5ABF	ES5BBF	ES5DBF	ES5GBF	ES5JBF	UNITS
Marking Code		MDD E5AB	MDD E5BB	MDD E5DB	MDD E5GB	MDD E5JB	
Maximum repetitive peak reverse voltage	V_{RMM}	50	100	200	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	V
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$				5.0		A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}				150		A
Maximum instantaneous forward voltage at 5.0A	V_F		1		1.25	1.70	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R			10.0	100.0		μA
Maximum reverse recovery time (NOTE 1)	t_{rr}			35			ns
Typical junction capacitance (NOTE 2)	C_J			95.0			pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$			45.0			$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	T_J, T_{STG}			-55 to +150			°C

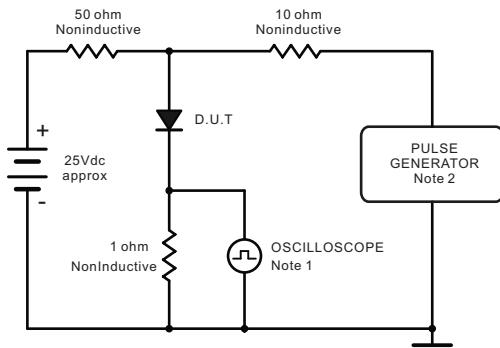
Note: 1.Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$

2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3.P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas



Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.

Fig.2 Maximum Average Forward Current Rating

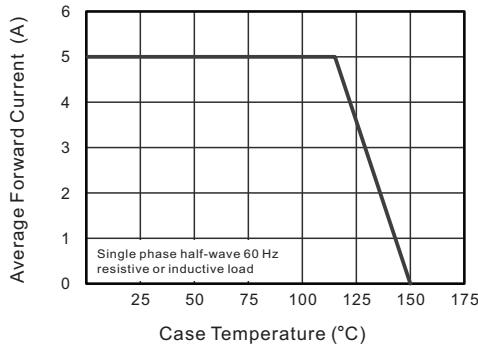


Fig.4 Typical Forward Characteristics

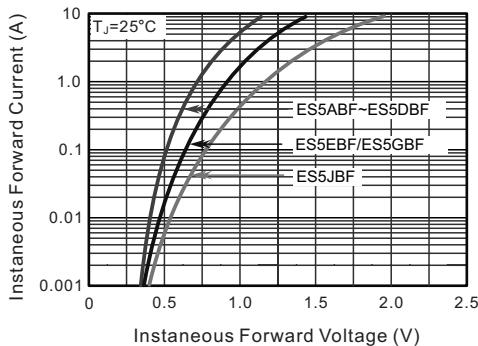
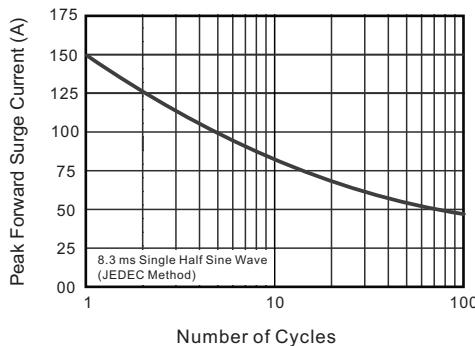


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

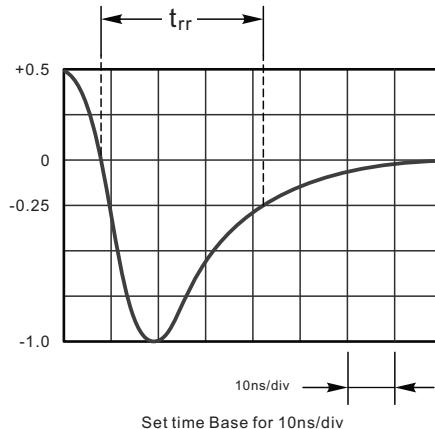


Fig.3 Typical Reverse Characteristics

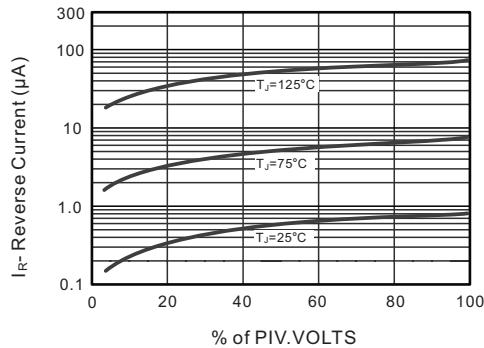
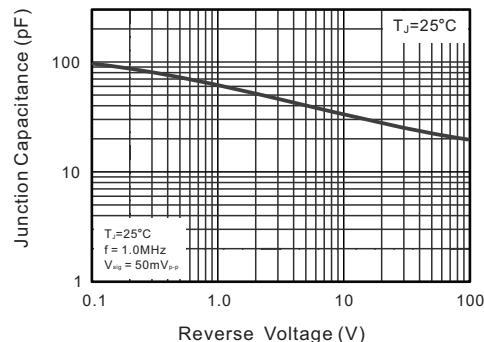
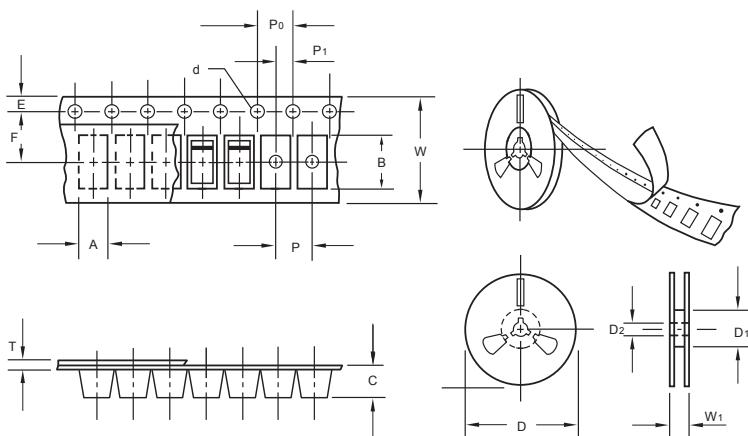


Fig.5 Typical Junction Capacitance





Packing information



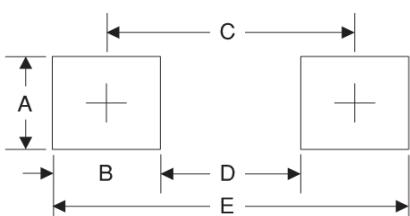
Item	Symbol	Tolerance	SMBF
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.61
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W1	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMBF	13"	5,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.54	0.100
B	1.8	0.071
C	4.8	0.189
D	3.0	0.118
E	6.6	0.260